Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.3 EP)
Lead Count	12
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.28E-02	86.91	869100	29.19	291862
Thermosets	Epoxy & Phenol Resin	Proprietary	1.88E-03	12.78	127800	4.29	42918
Other inorganic materials	Carbon black	1333-86-4	4.56E-05	0.31	3100	0.10	1041
Subtotal			1.47 E-02	100.00	1000000	33.58	335821

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.42 E-02	97.5	975000	55.21	552076
Copper & its alloys	Iron	7439-89-6	5.83 E-04	2.35	23500	1.33	13306
Copper & its alloys	Zinc	7440-66-6	2.98 E-05	0.12	1200	0.07	679
Copper & its alloys	Phosphorus	7723-14-0	7.44 E-06	0.03	300	0.02	170
Subtotal			2.48 E-02	100.00	1000000	56.62	566231

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.72 E-04	100.0	1000000	1.31	13060

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.15 E-04	100.0	1000000	1.63	16325

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.24 E-04	99.0	990000	0.74	7388
Precious metals	Palladium	7440-05-3	3.27 E-06	1.0	10000	0.01	75
Subtotal			3.27 E-04	100.0	1000000	0.75	7463

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.92 E-03	100.0	1000000	4.38	43843

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.87 E-04	77.71	777100	1.34	13411
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.35 E-05	3.11	31100	0.05	537
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.35 E-05	3.11	31100	0.05	537
Other organic materials	Butyrolactone, gamma-	96-48-0	2.35 E-05	3.11	31100	0.05	537
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.35 E-05	3.11	31100	0.05	537
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.35 E-05	3.11	31100	0.05	537
Other organic materials	Organosilane	TS ref# 10001	2.35 E-05	3.11	31100	0.05	537
Other inorganic materials	Copper(II) oxide	1317-38-0	2.35 E-05	3.11	31100	0.05	537
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.93 E-06	0.52	5200	0.009	90
Subtotal			7.56 E-04	100.0	1000000	1.73	17257

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.38 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.